

SURFACE MOUNT RECTIFIERS

REVERSE VOLTAGE: 50 - 1000 V
CURRENT: 1.0 A

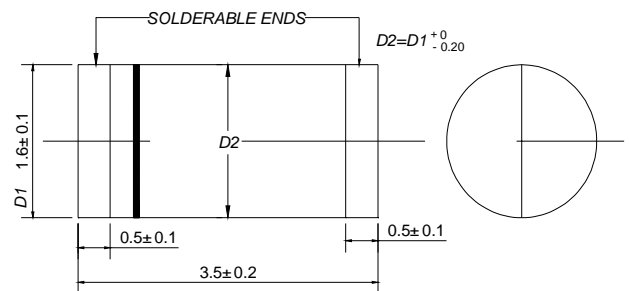
FEATURES

- ◇ Plastic package has underwriters laboratory flammability classifications
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering: 250°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC DO-213AA, molded plastic over passivated chip
- ◇ Terminals: Solder Plated, solderable per ML-STD-750, Method 2026
- ◇ Polarity: Color band denotes cathode end
- ◇ Weight: 0.0014 ounces, 0.036 gram

DO - 213AA



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		GL34A	GL34B	GL34D	GL34G	GL34J	GL34K	GL34M	UNITS
Polarity color bands (2nd Band)		Gray	Red	Orange	Yellow	Green	Blue	Violet	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RWS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current @ $T_A=75^\circ\text{C}$	$I_{F(AV)}$	0.5							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	10.0							A
Maximum instantaneous forward voltage at 0.5 A	V_F	1.2				1.3			V
Maximum DC reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	5.0				50.0			μA
Typical junction capacitance(NOTE 2)	C_J	4.0							pF
Typical reverse recovery time(NOTE3)	t_{rr}	1.5							μS
Typical thermal resistance (NOTE 4)	$R_{\theta JA}$	150							$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55-----+150							$^\circ\text{C}$
Storage temperature range	T_{STG}	-55-----+150							$^\circ\text{C}$

NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0volts

www.galaxycn.com

2. Thermal resistance from junction to ambient and junction to lead P.C.B mounted on 0.27"X0.27"(7.0X7.0mm2) copper pad areas

3. Measured with $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$.

4. Thermal resistance from junction to ambient and junction to lead P.C.B. mounted on 0.27"X0.27"(7.0X7.0mm2) copper pad areas

FIG.1 – FORWARD DERATING CURVE

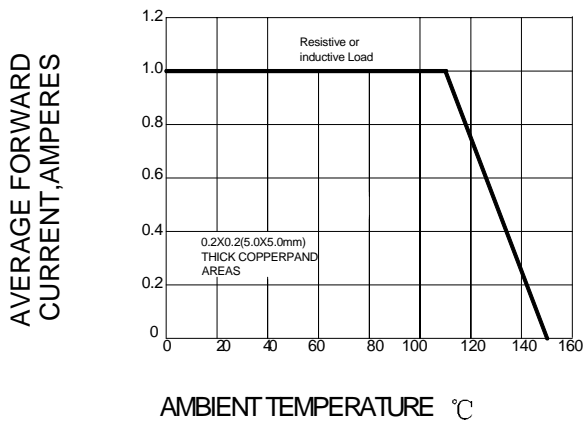


FIG.2 PEAK FORWARD SURGE CURRENT

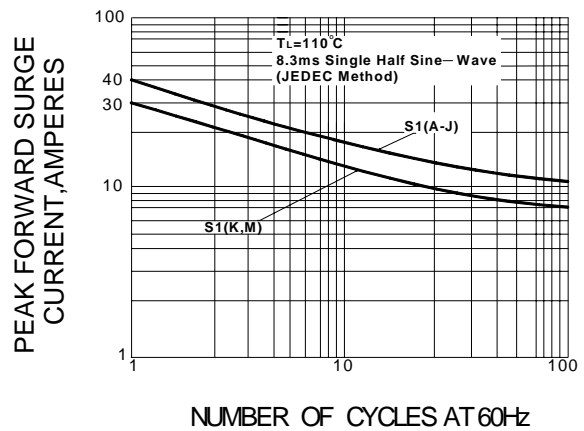


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

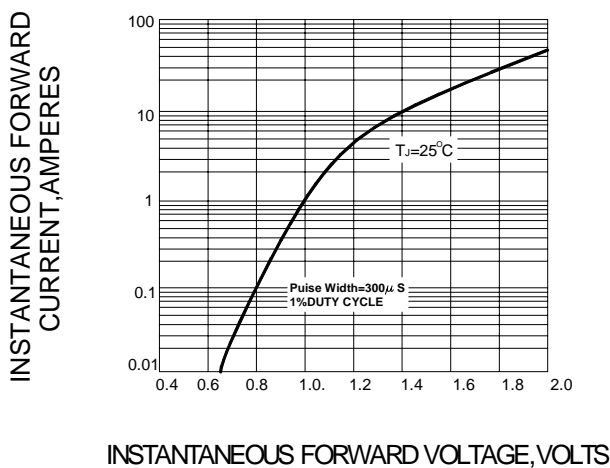


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

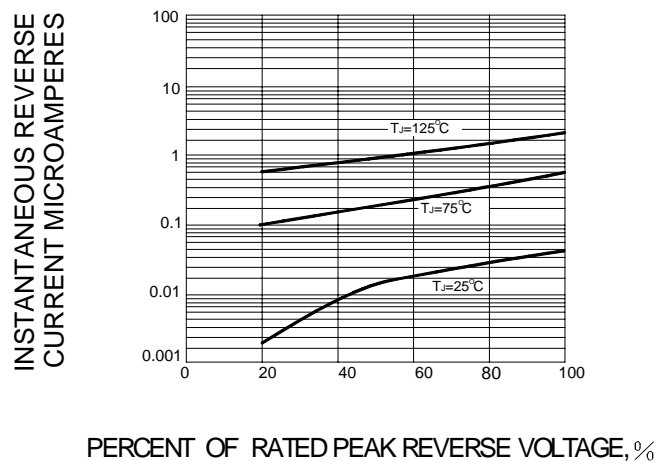


FIG.5-TYPICAL JUNCTION CAPACITANCE

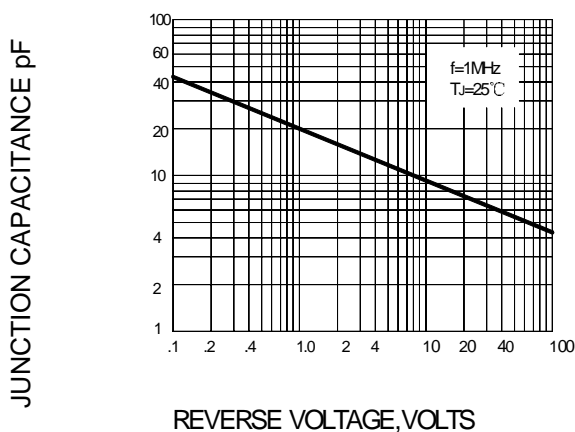


FIG.6-TRANSIENT THERMAL IMPEDANCE

